

Addition to the family of the series 53xx

Our Series 53 bonder family has become even more versatile: the new **USG 16 digital ultrasonic generator** is a real all-rounder and first time available in the manual Bondersegment. It works with thin wires of gold and aluminum as well as heavy wire and can be freely programmed to any working frequency between 40 and 160 kHz.

This is perfectly matched by our new transducers for manual thin-wire bonding, which are adapted not only to one but to two operating frequencies, for example to 69 kHz and 130 kHz.



53xx Series BDA



USG-16 Digital Generator

Depending on the operator selection, the digital generator adjusts itself exactly to one of the two operating frequencies of the transducer. This is particularly useful for some components where, for example, bonding is required on package pins. The resonance of such pins can cause bonding problems.

The problem is then usually solved simply by switching to the second operating frequency. Even different substrate surfaces, such as sputtered metallizations or rough thick-film pastes, can sometimes be bonded better with different ultrasonic frequencies.

The series 53xx now even more flexible

In line with the new digital generator, the Series 53 models have become **even more flexible**: all bond heads can now be replaced by the user in **just a few simple steps**. On the 53XX-BDA, which is already capable of ball bonding and deep-access bonding for thin wire, the user can change the bond head for heavy wire bonding **within a few minutes**, creating the Model 5350. The digital ultrasonic generator USG 16 controls both transducer types effortlessly - nobody else in the world offers a **more economical pathway** to heavy wire bonding.

And best of all: even existing Series 53 bonders can take advantage of these benefits with the new digital ultrasonic generator.

Did our newsletter inspire new ideas? Do you think we've forgotten something? Contact and tell us your process requirements.